

■ Features

- High isolation 3750 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- REACH compliance
- Halogen free
- MSL class 1
- Regulatory Approvals
 - UL - UL1577
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC – GB4943.1-2022

■ Applications

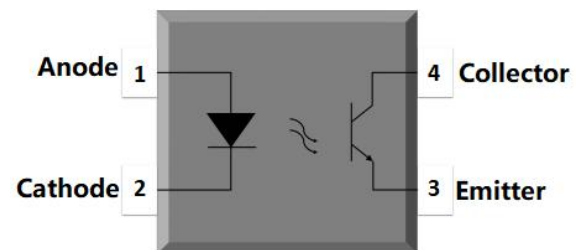
- Switch mode power supplies
- Programmable controllers
- Office equipment
- System appliances, measuring instruments
- Telecommunication equipments
- Signal transmission between circuits of different potentials and impedances
- Home appliances, such as fan heaters, etc.

■ Description

The MPC356 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic SOP4 package.

With the robust coplanar double mold structure, MPC356 series provide the most stable isolation feature.

■ Schematic





MPC356 Series

SOP4, DC Input Photo Transistor Coupler

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT	REMARK
INPUT				
Forward Current	I_F	60	mA	
Peak Forward Current	I_{FP}	1	A	(Note 1)
Reverse Voltage	V_R	6	V	
Input Power Dissipation	P_I	100	mW	
OUTPUT				
Collector - Emitter Voltage	V_{CEO}	80	V	
Emitter - Collector Voltage	V_{ECO}	7	V	
Collector Current	I_C	50	mA	
Output Power Dissipation	P_O	150	mW	
COMMON				
Total Power Dissipation	P_{tot}	200	mW	
Isolation Voltage	V_{iso}	3750	V _{rms}	(Note 2)
Operating Temperature	T_{opr}	-55~110	°C	
Storage Temperature	T_{stg}	-55~125	°C	
Soldering Temperature	T_{sol}	260	°C	

Note 1. 100μs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%



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ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C							
PARAMETER	SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	REMARK
INPUT							
Forward Voltage	V _F	-	1.24	1.4	V	I _F =10mA	
Reverse Current	I _R	-	-	10	μA	V _R =6V	
Input Capacitance	C _{in}	-	10	-	pF	V=0, f=1kHz	
OUTPUT							
Collector Dark Current	I _{CEO}	-	-	100	nA	V _{CE} =20V, I _F =0	
Collector-Emitter Breakdown Voltage	BV _{CEO}	80	-	-	V	I _C =0.1mA, I _F =0	
Emitter-Collector Breakdown Voltage	BV _{ECO}	6	-	-	V	I _E =0.1mA, I _F =0	
TRANSFER CHARACTERISTICS							
Current Transfer Ratio	MPC356	CTR	50	-	600	I _F =5mA, V _{CE} =5V	
	MPC356A		80	-	160		
	MPC356B		130	-	260		
	MPC356C		200	-	400		
	MPC356D		300	-	600		
Collector-Emitter Saturation Voltage	V _{CE(sat)}	-	0.06	0.2	V	I _F =20mA, I _C =1mA	
Isolation Resistance	R _{ISO}	10 ¹²	10 ¹⁴	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C _{IO}	-	0.4	1	pF	V=0, f=1MHz	
Cut-off Frequency	f _c	-	80	-	kHz	V _{CE} =2V, I _C =2mA R _L =100Ω, -3dB	(Note 4)
Response Time (Rise)	t _r	-	6	18	μs	V _{CE} =2V, I _C =2mA R _L =100Ω	(Note 3)
Response Time (Fall)	t _f	-	8	18	μs		

Note 3. Fig.12&13

Note 4. Fig.14

CHARACTERISTIC CURVES

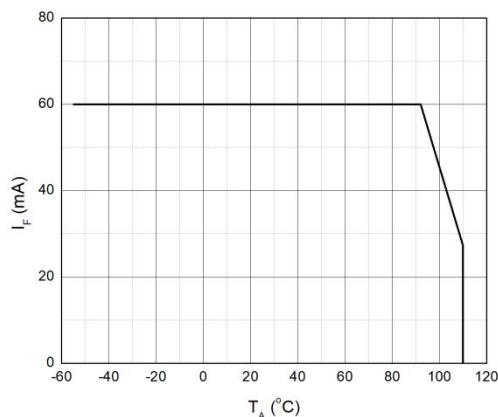


Fig.1 Forward Current vs. Ambient Temperature

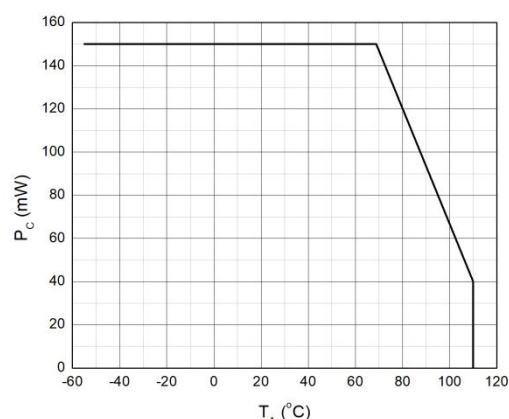


Fig.2 Collector Power Dissipation vs. Ambient Temperature

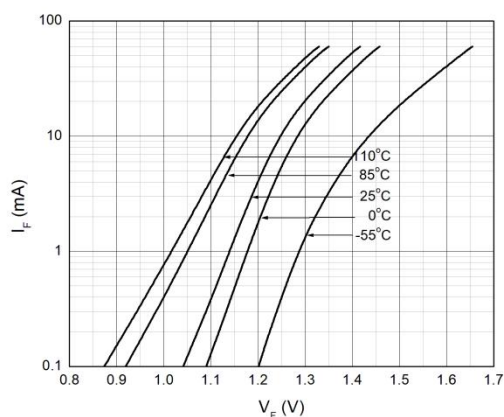


Fig.3 Forward Current vs. Forward Voltage

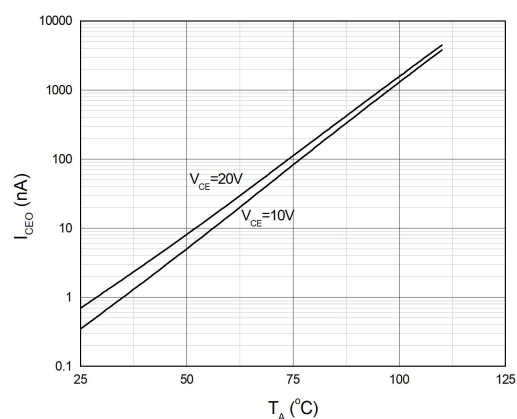


Fig.4 Collector Dark Current vs. Ambient Temperature

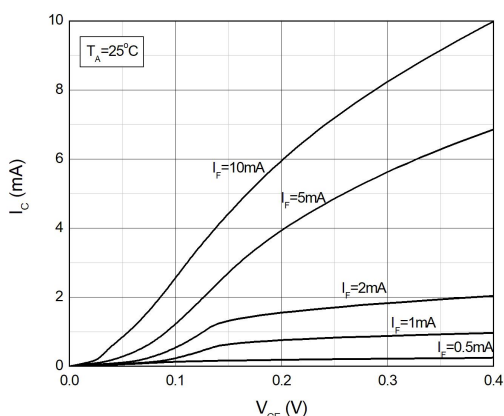


Fig.5 Collector Current vs. Collector-emitter Voltage

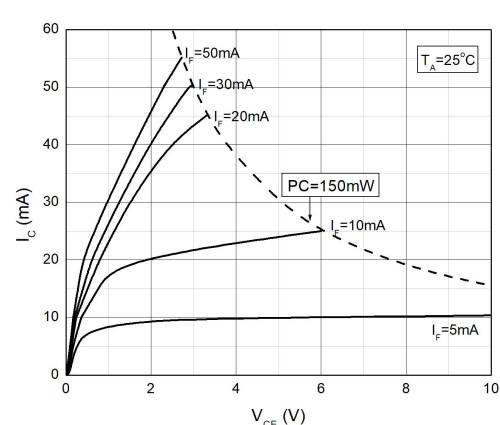


Fig.6 Collector Current vs. Collector-emitter Voltage

CHARACTERISTIC CURVES

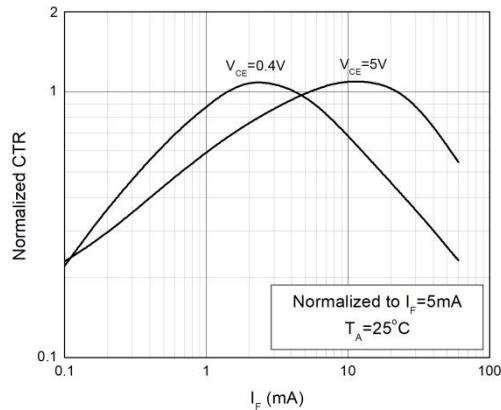


Fig.7 Normalized Current Transfer Ratio vs. Forward Current

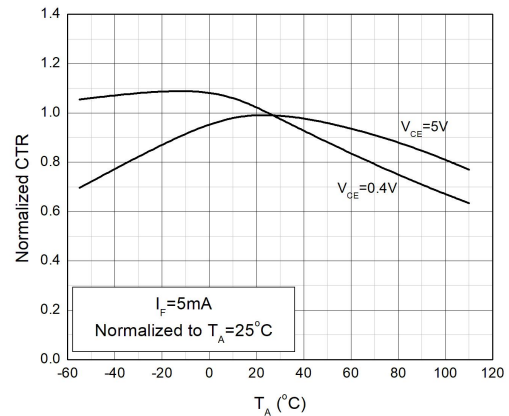


Fig.8 Normalized Current Transfer Ratio vs. Ambient Temperature

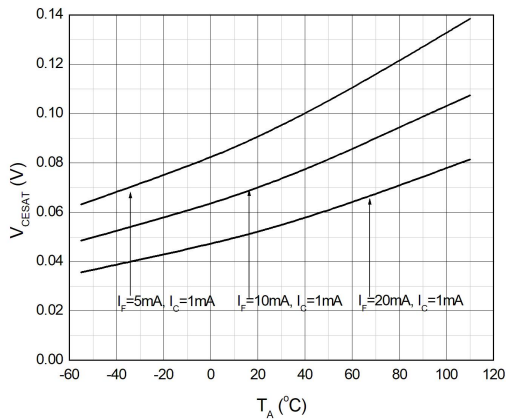


Fig.9 Collector-emitter Saturation Voltage vs. Ambient Temperature

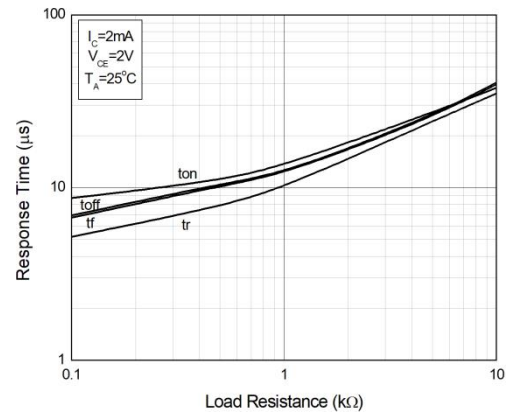


Fig.10 Switching Time vs. Load Resistance

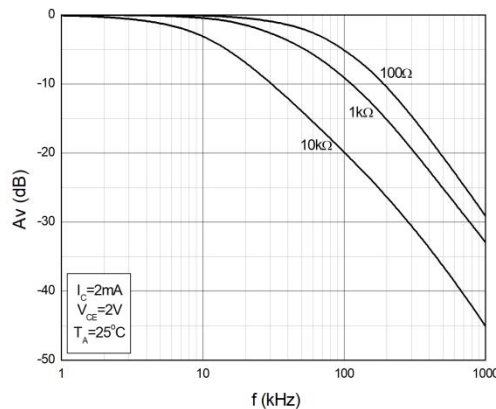


Fig.11 Frequency Response

TEST CIRCUITS

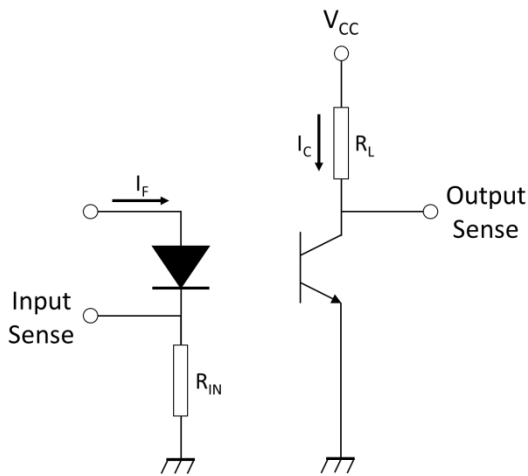


Fig.12 Test Circuits of Response Time

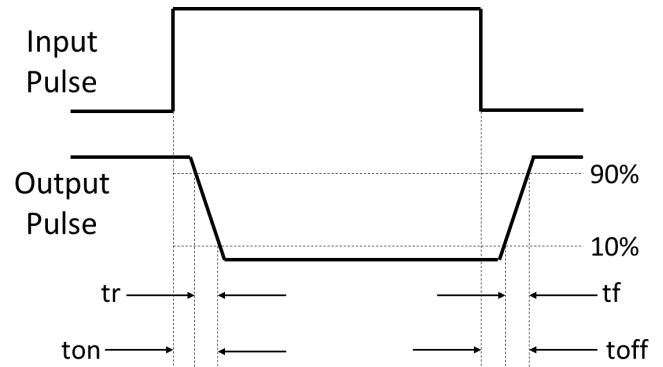


Fig.13 Curves of Response Time

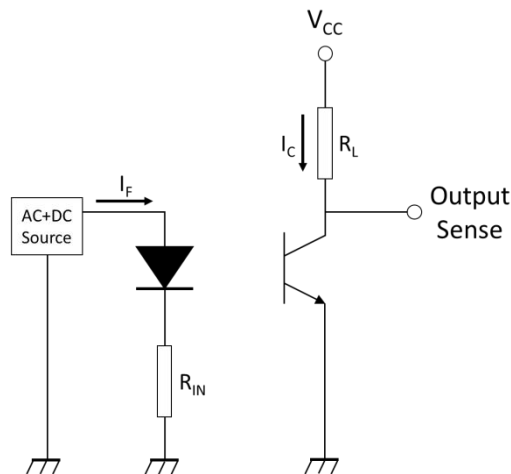
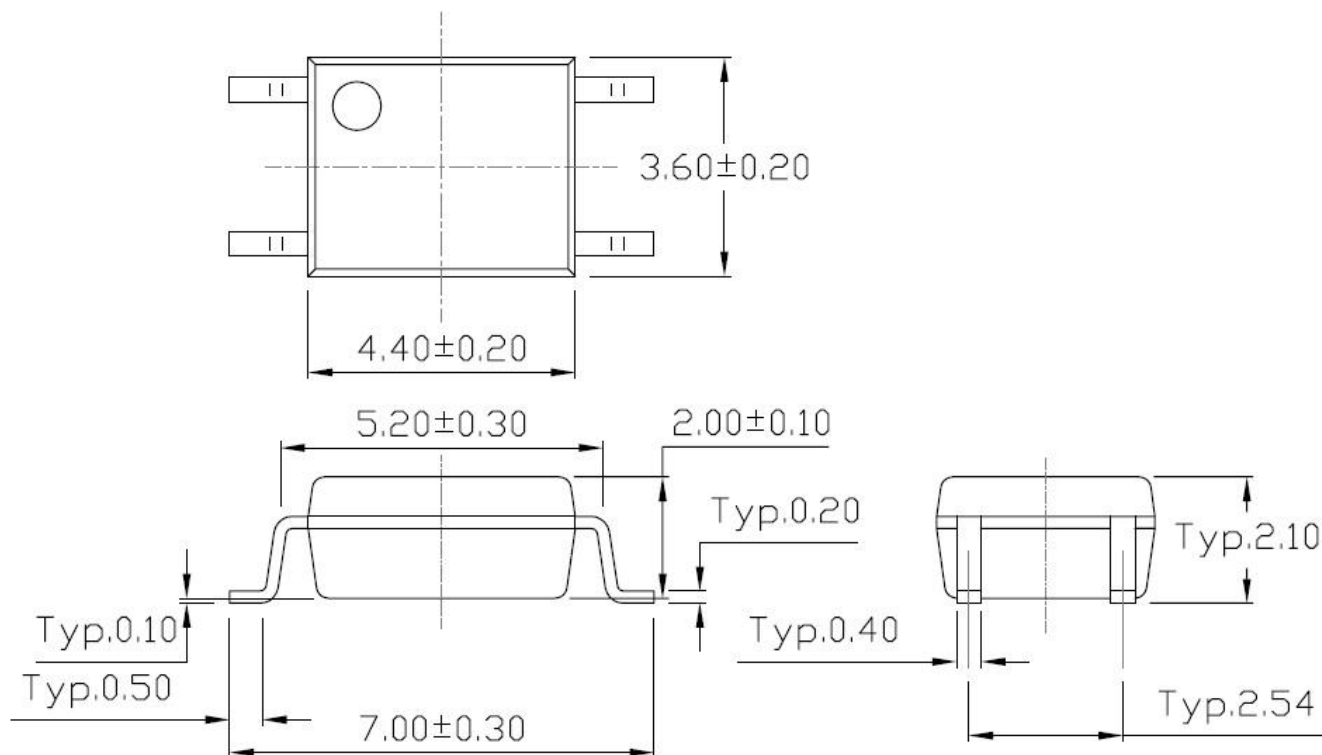
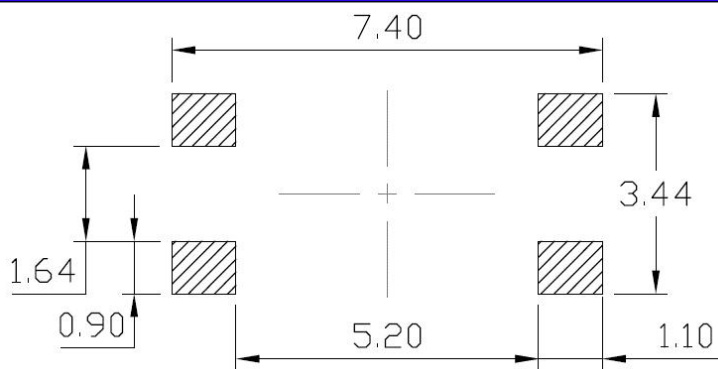


Fig.14 Test Circuits of Frequency Response

PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

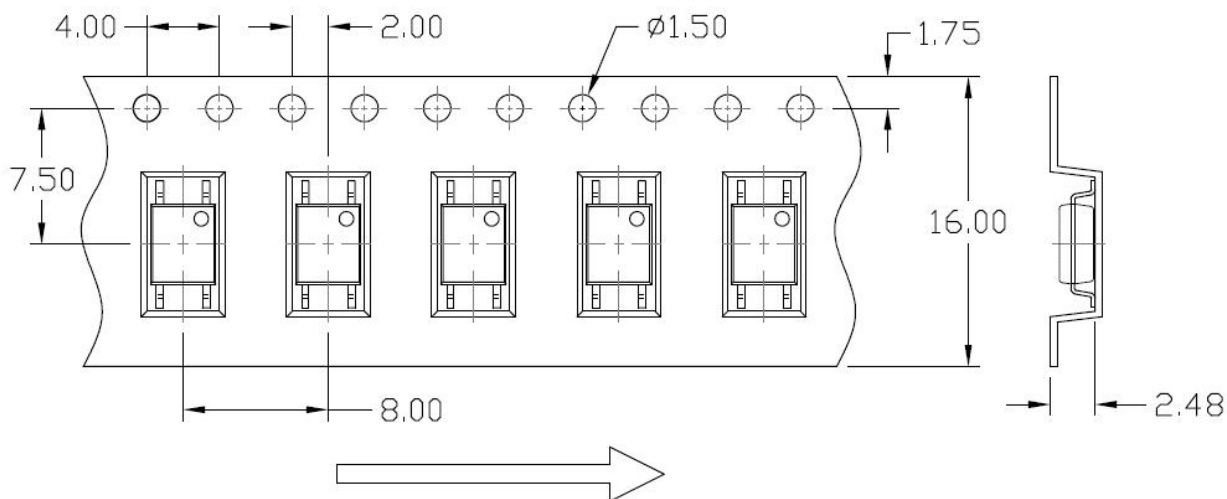


Recommended Solder Mask (Dimensions in mm unless otherwise stated)

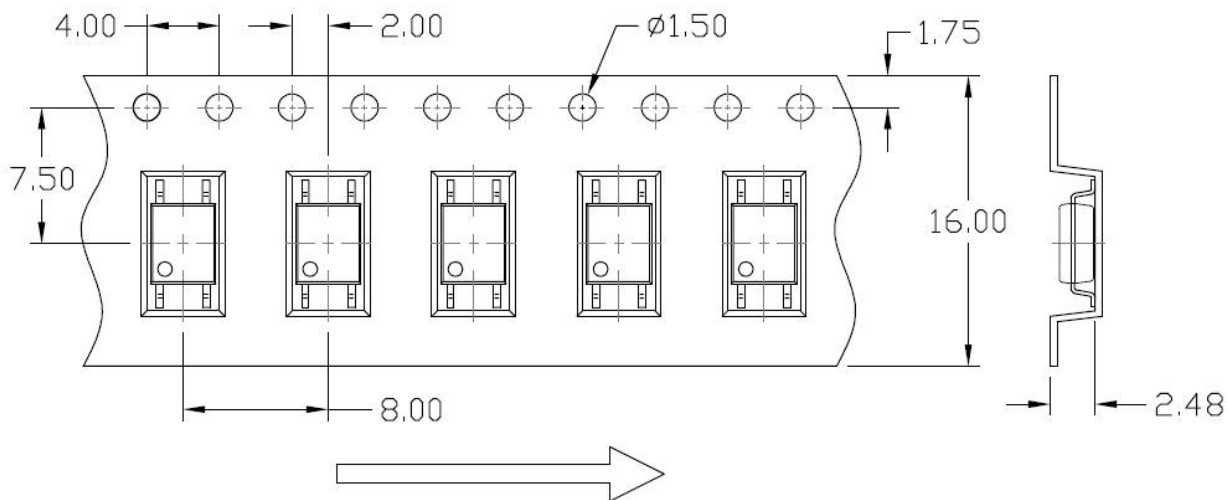


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1



Option T2



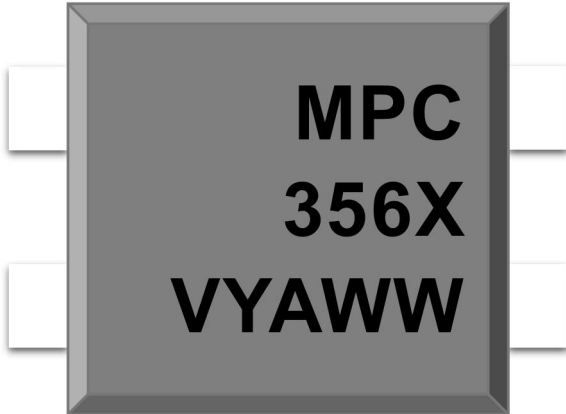


MPC356 Series

SOP4, DC Input Photo Transistor Coupler

ORDERING AND MARKING INFORMATION

MARKING INFORMATION



MPC : Company Abbr.
356 : Part Number
X : CTR Rank
V : VDE Option
Y : Fiscal Year
A : Manufacturing Code
WW : Work Week

ORDERING INFORMATION

MPC356XN(Z)-GV

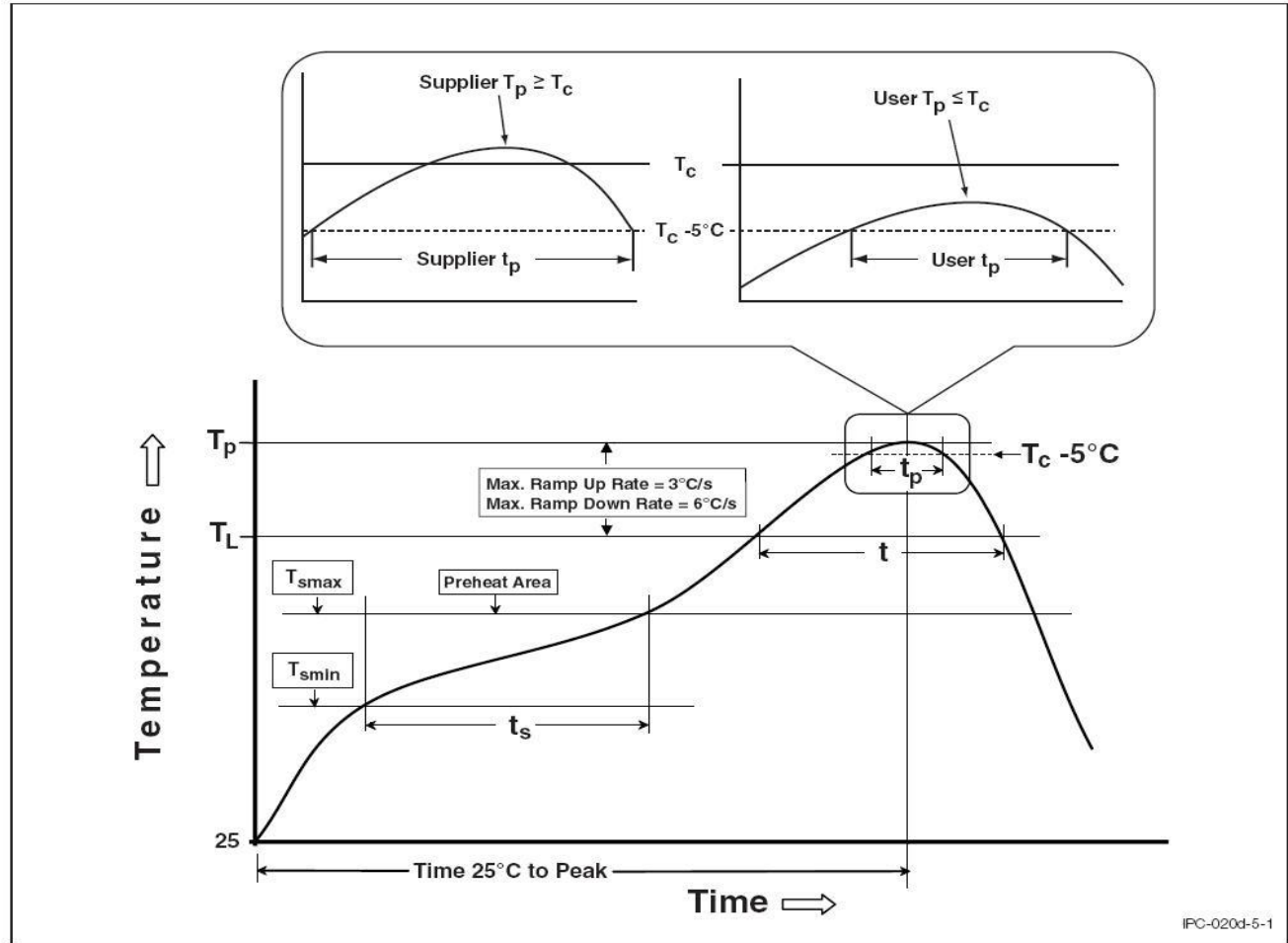
MPC – Company Abbr. 356 – Part Number X – Rank1 (A/B/C/D or None) N – Rank2 (1~9 or None)	Z – Tape and Reel Option (T1/T2) G – Green V – VDE Option (V or None)
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PACKING QUANTITY

Option	Quantity	Quantity – Inner box	Quantity – Outer box
T1	3000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 45k Units
T2	3000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 45k Units

REFLOW INFORMATION

REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150°C
Temperature Max. (T _{smax})	150	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.	3°C/second max.
Liquidous Temperature (T _L)	183°C	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



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DISCLAIMER

- Our company is continually improving the quality, reliability, function and design. Our company reserves the right to make changes without further notices.
- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Immerge unit's body in solder paste is not recommended.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.

■ Revision History

Version	Date	Subjects (major changes since last revision)
1.0	2018-12-21	Datasheet Complete
1.1	2023-07-05	Upgrade Datasheet